

PART INFORMATION

Mfg Item Number	FXLC95000CL
Mfg Item Name	LGA 24LD 3*5*1P0.5

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-07-07
Response Document ID	00AKK50008S278M1.0
Contact Name	Freescale Semiconductor Inc
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
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Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	
EU RoHS Exemption(s)	7c-I

MANUFACTURING

Mfg Item Number	FXLC95000CL
Mfg Item Name	LGA 24LD 3*5*1P0.5
Version	ALL
Weight	0.033800
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Bonding Wire	0.0001						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0001	g	1000000	100	2958	0.2958
Die Encapsulant, Halogen-free	0.019						g				
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000095	g	4994	0.4994	2810	0.281
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.001044	g	54936	5.4936	30887	3.0887
Die Encapsulant, Halogen-free		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.000831	g	43749	4.3749	24585	2.4585
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60876-86-0		0.0158	g	831596	83.1596	467466	46.7466
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000019	g	999	0.0999	562	0.0562
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.001211	g	63726	6.3726	35828	3.5828
Silicon Semiconductor Die	0.0025						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00005	g	20000	2	1479	0.1479
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00245	g	980000	98	72485	7.2485
Organic Substrate, Halogen-free	0.0079						g				
Organic Substrate, Halogen-free		Metals	Proprietary Material-Other aluminum compounds	-		0.000002	g	224	0.0224	59	0.0059
Organic Substrate, Halogen-free		Metals	Arsenic, metal	7440-38-2		0.000001	g	143	0.0143	29	0.0029
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.000275	g	34768	3.4768	8136	0.8136
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.002814	g	356209	35.6209	83254	8.3254
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.000123	g	15581	1.5581	3639	0.3639
Organic Substrate, Halogen-free		Metals	Talc	14807-96-6		0.000032	g	4025	0.4025	946	0.0946
Organic Substrate, Halogen-free		Metals	Nickel, metal	7440-02-0		0.000722	g	91445	9.1445	21360	2.136
Organic Substrate, Halogen-free		Plastics/polymers	Proprietary Material-Other polymers	-		0.002411	g	305203	30.5203	71331	7.1331
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.00151	g	191172	19.1172	44674	4.4674
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.000008	g	1006	0.1006	236	0.0236
Organic Substrate, Halogen-free		Metals	Copper phthalocyanine	147-14-8		0.000002	g	224	0.0224	59	0.0059
Non-Conductive Epoxy/Adhesive	0.0007						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Ortho-Cresol, Polymer with 1-Chloro-2,3-Epoxypropane and Formaldehyde	20690-82-2		0.000105	g	150000	15	3106	0.3106
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Phenol-p-xylylene dimethyl ether copolymer	26834-02-6		0.000105	g	150000	15	3106	0.3106
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silane Dichlorodimethyl	68611-44-9		0.000035	g	50000	5	1035	0.1035
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Copolymer of ethylacrylate, butylacrylate, acrylonitrile, glycidymethacrylate	58152-79-7		0.000455	g	650000	65	13461	1.3461
Pb Glass Frit Semiconductor Di	0.0036				7c-I		g				
Pb Glass Frit Semiconductor Di		Metals	Lead titanium oxide (PbTiO3)	12060-00-3		0.000037	g	10381	1.0381	1094	0.1094
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.000036	g	9943	0.9943	1065	0.1065
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.000036	g	9943	0.9943	1065	0.1065
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.003491	g	969733	96.9733	103285	10.3285

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v0.9 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/FXLC95000CL_IPC1752_v09.xml

http://www.freescale.com/mcdfs/FXLC95000CL_IPC1752_v11.xml

http://www.freescale.com/mcdfs/FXLC95000CL_IPC1752A.xml